

This assignment agreement is applicable to an invention entitled (invention title) _____

STACKED CHIP SCALE PACKAGE STRUCTURE

The PATENT RIGHT referred to in this agreement are:

- (check one) a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Assignment
- U.S. Patent Application Serial No. _____, filed _____
- U.S. Patent No. 6,633,086, issued 10/14/2003

The PATENT RIGHT assigned under this agreement are:

- (check one) U.S. Patent rights only
- worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. Patent Application identified above.

The ASSIGNOR(S) referred to in this agreement is (or are):

(Full name of first assignor) VATE TECHNOLOGY CO., LTD.
 (Address) NO. 9 LI-HSIN RD. V. SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN, R.O.C.
 (Full name of second joint inventor, if any) _____
 (Address) _____
 (Full name of third joint inventor, if any) _____
 (Address) _____

The First ASSIGNEE referred to in this agreement is:

(Name of Assignee) Global Advanced Packaging Technology H.K. Limited
 (Address) Unit A, 19/F, V Ga Building, 532 Castle Peak Road, Kowloon, Hong Kong.

The Second ASSIGNEE referred to in this agreement is:

(Name of Assignee) _____
 (Address) _____

The Third ASSIGNEE referred to in this agreement is:

(Name of Assignee) _____
 (Address) _____

The First ASSIGNEE is

- (check one) an individual
- a partnership
- a Corporation of Hong Kong
(state or Country)

The Second ASSIGNEE is

- (check one) an individual
- a partnership
- a Corporation of _____
(state or Country)

The Third ASSIGNEE is

- (check one) an individual
- a partnership
- a Corporation of _____
(state or Country)

The ASSIGNOR(S), in consideration of \$1.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, have and do hereby assign the following to each ASSIGNEE; their successors and assigns:

- the full and exclusive right to the invention;
- an equal interest in and to the entire right, title and interest in and to the PATENT RIGHTS in the invention; all continuations, continuations-in-part, divisionals, re-issues, and re-examination patents and patent applications; and the right to claim priority under 35 U.S.C. 119, based on any earlier foreign applications for this invention.

As to all U.S. Patent Applications assigned under this Agreement, the ASSIGNOR(s) hereby authorize(s) and request(s) the Director of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE(s) as the ASSIGNEE(s) of an equal interest in the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE(s), their successors and assigns.

Further, the ASSIGNOR(s) agree(s) to communicate to said ASSIGNEE(s), or their representatives, any facts known to the ASSIGNOR(s) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, Continuation-in part, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE(s), make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE(s), their successors and assigns, to obtain an enforced proper protection for said invention.

Wang - Cheng - Fan
 (Signature of sole or first assignor) WANG, CHENG - FAN
 President

9/21/02
 (Date)

(Signature of second assignor, if any)

(Date)

(Signature of third assignor, if any)

(Date)

(Signature of fourth assignor, if any)

(Date)